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Solus Advanced Materials Kicks off Copper Foil Mass Production for 'Company N' — Supplied via Doosan

- **'Company N' to Feature Solus Copper Foil in Upcoming AI Accelerator, Launching This Year**
- **South Korea's First-Ever Approval Validates Low-Light Copper Foil Tech; Global Big Tech Demand Secured**
- **CEO Keunman Kwak Aims High: "Supplying All Three Major North American GPU Firms Is Our Goal"**

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Solus Advanced Materials has begun mass production of copper foil for next-generation AI accelerators developed by a major North American GPU company — marking for the first time a Korean firm has secured product approval and reached mass production of copper foil for AI accelerator.

Solus announced it has received final production approval from the North American GPU manufacturer, referred to as "Company N," and will supply its high-end Hyper Very Low Profile (HVLP) copper foil to Doosan Corporation's Electronic Business Group, which manufactures Copper Clad Laminates (CCL). It follows rigorous performance evaluation process conducted by both Doosan and Company N, solidifying Solus' status as a world-leading producer of ultra-low-roughness copper foil.

HVLP copper foil is a high-end product with surface roughness under 0.6 micrometers, designed to minimize signal loss in electronic devices. Its high signal integrity makes it ideal not only for AI accelerators but also for 5G infrastructure and high-efficiency network substrates.

Solus' HVLP foil will be integrated into Doosan's CCLs and embedded into Company N's next-generation AI accelerator, set to launch later this year.

Considering that global big tech companies typically go through complex qualification processes over several years and build long-term partnerships with selected suppliers, this milestone demonstrates that Solus has secured a reliable and high-growth customer base.

Solus is the only copper foil manufacturer globally capable of reliably mass-producing high-spec materials with exceptionally uniform surfaces using its advanced sensor and drum control technologies. This technological strength is based on over 65 years of manufacturing know-how from Circuit Foil Luxembourg (CFL), its printed circuit board (PCB) copper foil factory founded in 1960. Thanks to this edge, Solus maintains the No.1 global market share in the low-roughness copper foil segment.

CEO Keunman Kwak stated, "It is a significant achievement that our HVLP copper foil has successfully entered mass production in the rapidly growing AI accelerator market following the rise of ChatGPT." He added, "In addition to 'Company N', which recently approved mass production, we've also received product approval from 'Company I', and performance testing is currently underway with Company A. Our ultimate goal is to supply copper foil to all three major North American GPU companies."

